

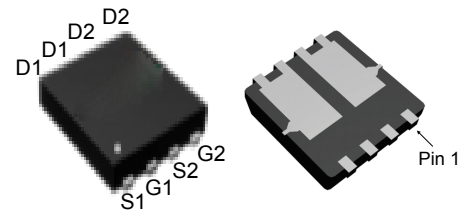
Features

- 40V/9A
 $R_{DS(ON)} = 25m\Omega (typ.) @ V_{GS} = 10V$
 $R_{DS(ON)} = 35m\Omega (typ.) @ V_{GS} = 4.5V$
- 100% UIS + R_g Tested
- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)

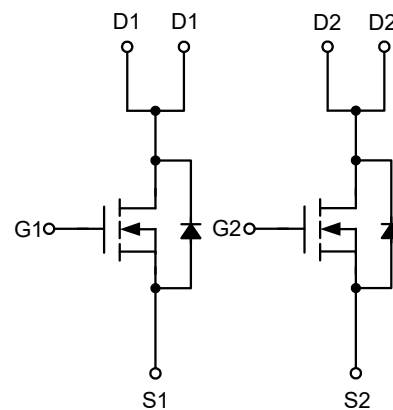
Applications

- Battery Protection.
- Load Switching.
- Bridge Topologies.

Pin Description



DFN3.3x3.3G-8_EP2



N-Channel MOSFET

Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ Unless Otherwise Noted)

Symbol	Parameter		Rating	Unit
Common Ratings				
V _{DSS}	Drain-Source Voltage		40	V
V _{GSS}	Gate-Source Voltage		±20	
T _J	Maximum Junction Temperature		150	°C
T _{STG}	Storage Temperature Range		-55 to 150	
I _S	Diode Continuous Forward Current	T _C =25°C	9	A
I _D	Continuous Drain Current	T _C =25°C	9	A
		T _C =100°C	6.75	
I _{DM} ^b	Pulsed Drain Current	T _C =25°C	27	
P _D	Maximum Power Dissipation	T _C =25°C	24	W
		T _C =100°C	9	
R _{θJC}	Thermal Resistance-Junction to Case	Steady state	5.3	°C/W
R _{θJA} ^d	Thermal Resistance-Junction to Ambient	t ≤ 10s	55	°C/W
		Steady state	93	
I _{AS} ^e	Avalanche Current, Single pulse	L=0.1mH	12	A
E _{AS} ^e	Avalanche Energy, Single pulse	L=0.1mH	7.2	mJ

Note a : Maximum continuous current is limited by bonding wire.

Note b : Pulse width limited by maximum junction temperature.

Note c : Surface mounted on 1in^2 pad area, $t \leq 10\text{s}$.

Note d : Surface mounted on 1in^2 pad area, steady state $t = 999\text{s}$.

Note e : UIS tested and pulse width limited by maximum junction temperature (initial temperature $T_J=25^{\circ}\text{C}$).

Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

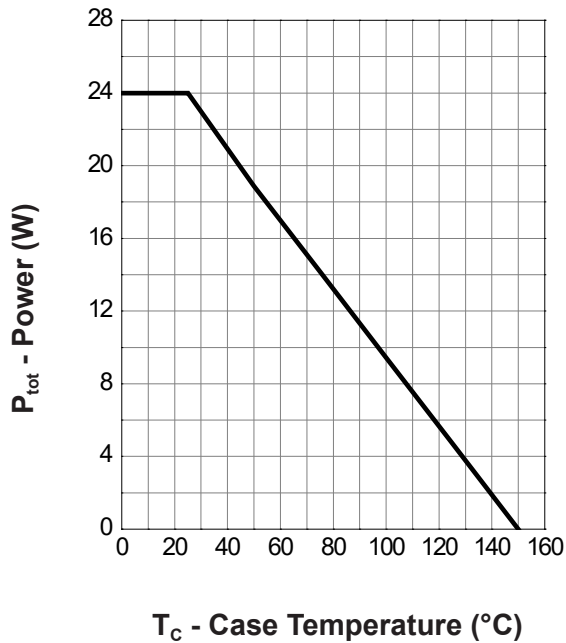
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250μA	40	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =32V, V _{GS} =0V T _J =85°C	-	-	1 30	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250μA	1.5	1.8	2.5	V
I _{GSS}	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
R _{DS(ON)} ^f	Drain-Source On-state Resistance	V _{GS} =10V, I _{DS} =10A T _J =125°C	-	25 30	28 -	mΩ
		V _{GS} =4.5V, I _{DS} =6A	-	35	40	
Gfs	Forward Transconductance	V _{DS} =5V, I _{DS} =6A	-	8.4	-	S
Diode Characteristics						
V _{SD} ^f	Diode Forward Voltage	I _{SD} =4A, V _{GS} =0V	-	0.8	1.1	V
t _{rr}	Reverse Recovery Time	I _{SD} =10A, dI _{SD} /dt=100A/μs	-	12	-	ns
t _a	Charge Time		-	7	-	
t _b	Discharge Time		-	5	-	
Q _{rr}	Reverse Recovery Charge		-	5	-	nC
Dynamic Characteristics ^g						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz	-	1.8	-	Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =20V, Frequency=1.0MHz	-	633	823	pF
C _{oss}	Output Capacitance		-	60	-	
C _{rss}	Reverse Transfer Capacitance		-	43	-	
t _{d(ON)}	Turn-on Delay Time	V _{DD} =20V, R _L =20Ω, I _{DS} =1A, V _{GEN} =10V, R _G =6Ω	-	10	18	ns
t _r	Turn-on Rise Time		-	9	17	
t _{d(OFF)}	Turn-off Delay Time		-	22	40	
t _f	Turn-off Fall Time		-	4	8	
Gate Charge Characteristics ^g						
Q _g	Total Gate Charge	V _{DS} =20V, V _{GS} =10V, I _{DS} =10A	-	11.4	17	nC
Q _g	Total Gate Charge	V _{DS} =20V, V _{GS} =4.5V, I _{DS} =10A	-	5.6	8	
Q _{gth}	Threshold Gate Charge		-	1	-	
Q _{gs}	Gate-Source Charge		-	1.8	-	
Q _{gd}	Gate-Drain Charge		-	2	-	

Note f : Pulse test ; pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

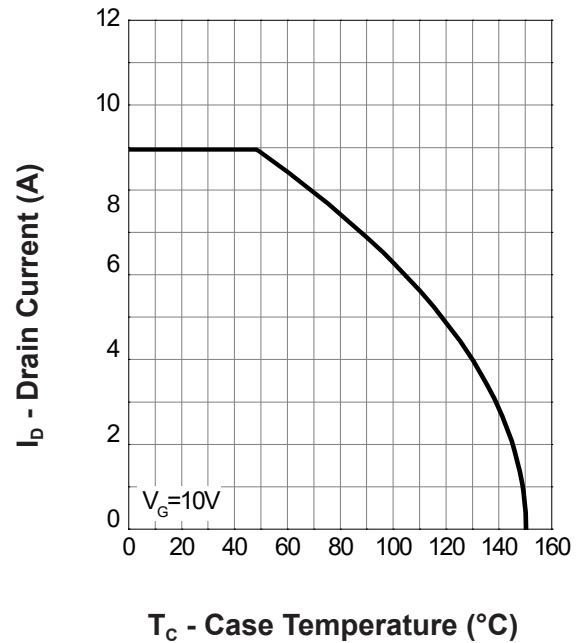
Note g : Guaranteed by design, not subject to production testing.

Typical Operating Characteristics

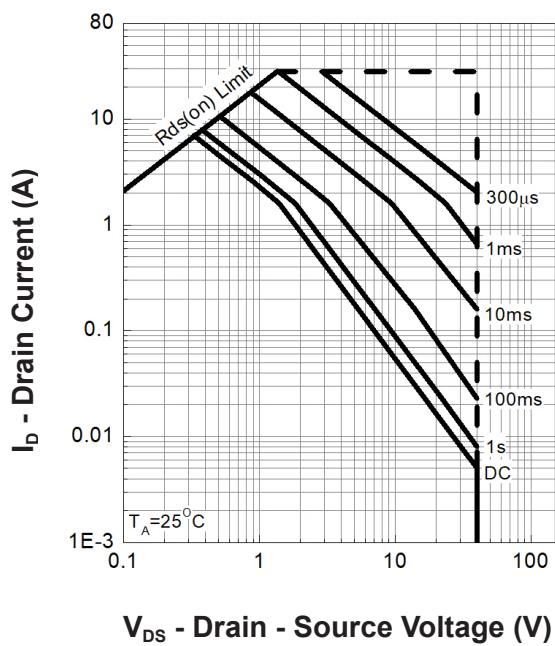
Power Dissipation



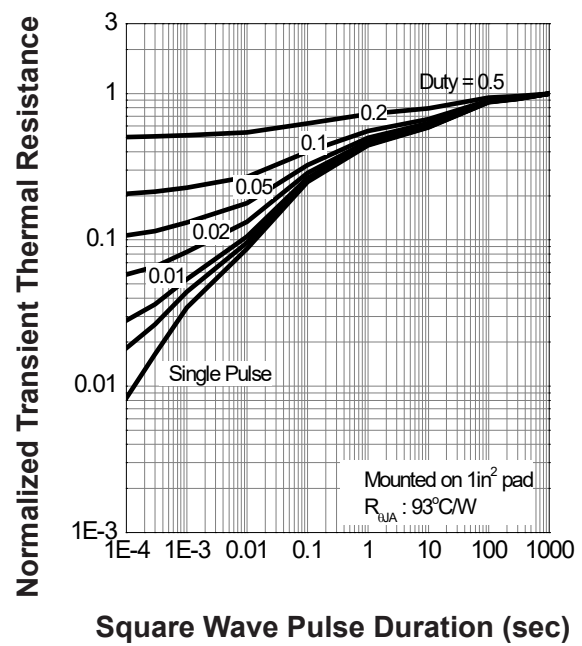
Drain Current



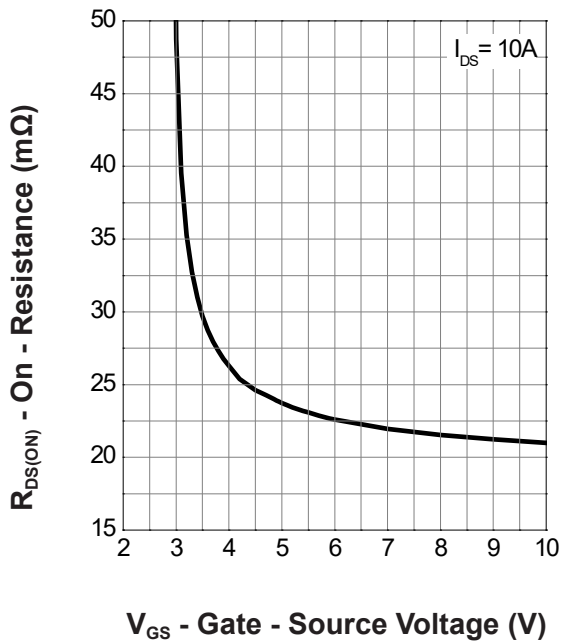
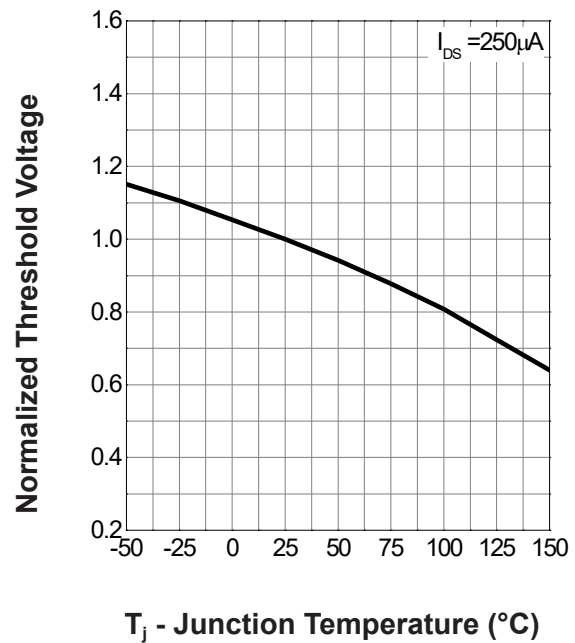
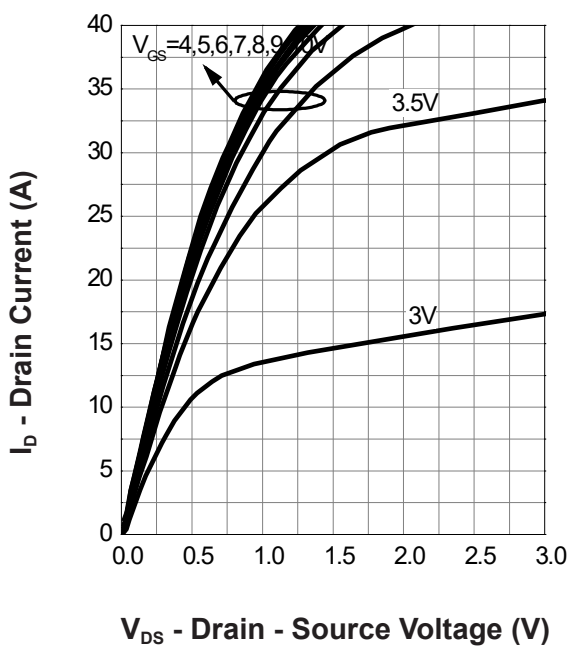
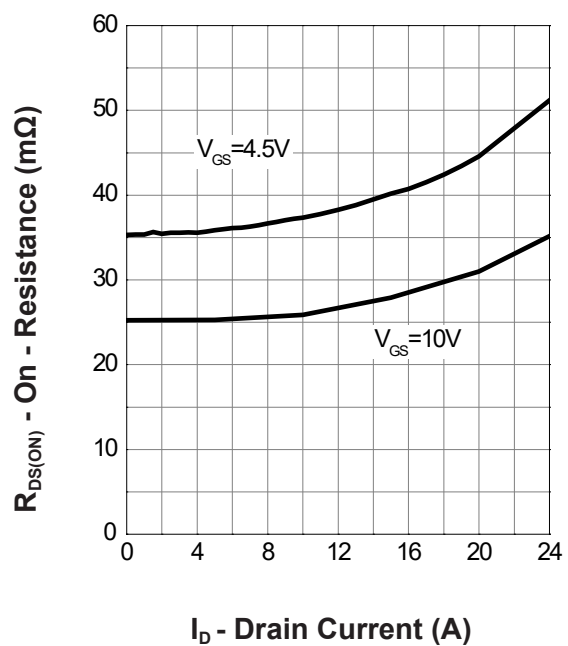
Safe Operation Area



Thermal Transient Impedance

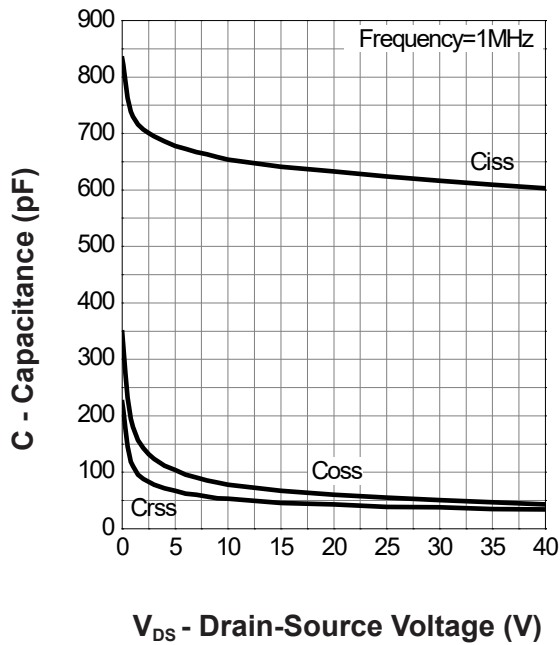


Typical Operating Characteristics(Cont.)

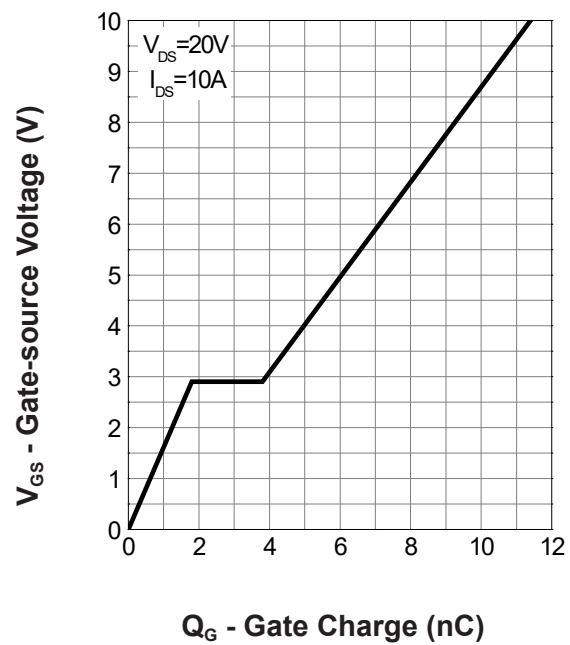
Gate-Source On Resistance

Gate Threshold Voltage

Output Characteristics

Drain-Source On Resistance


Typical Operating Characteristics(Cont.)

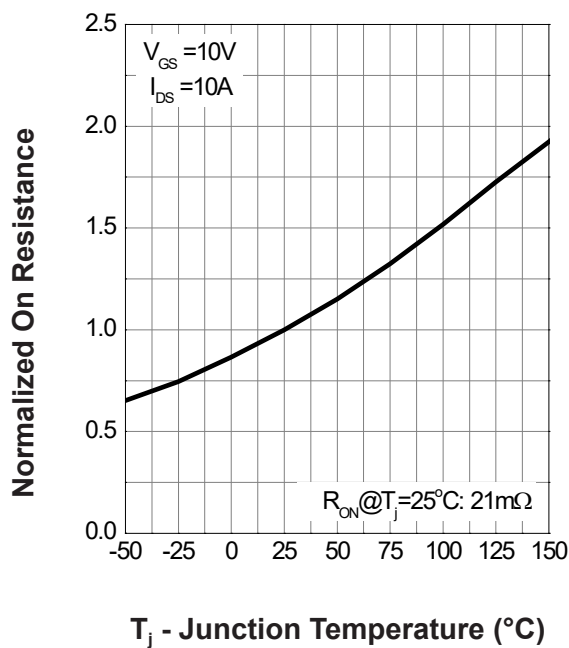
Capacitance



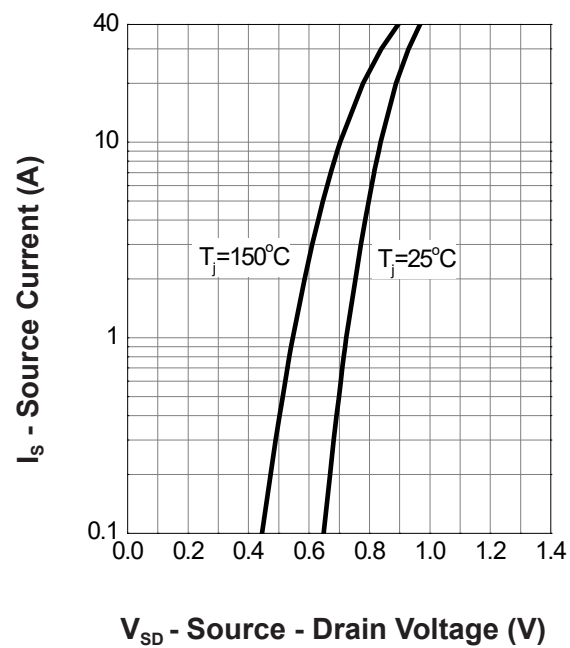
Gate Charge



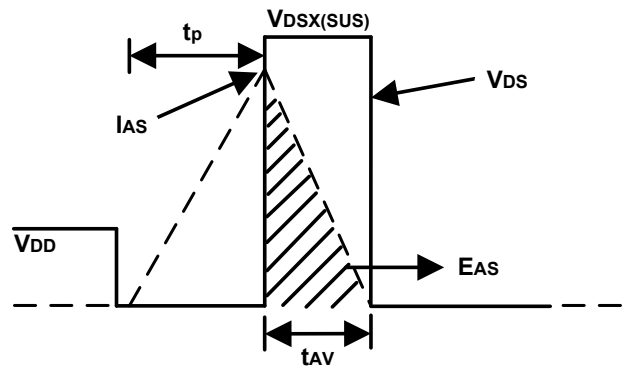
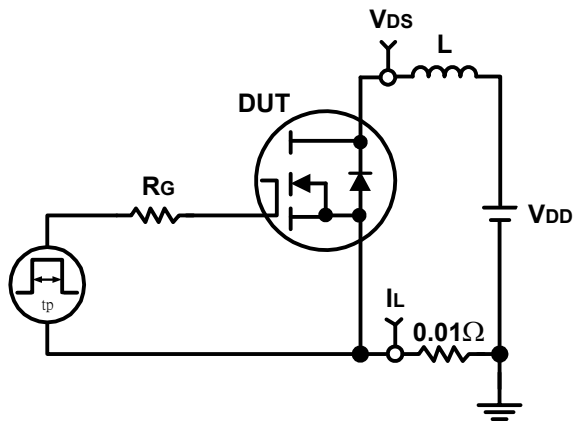
Drain-Source On Resistance



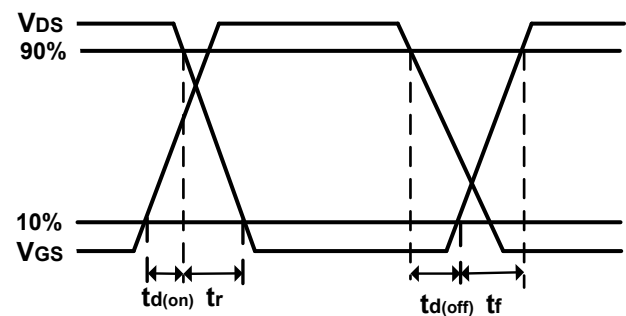
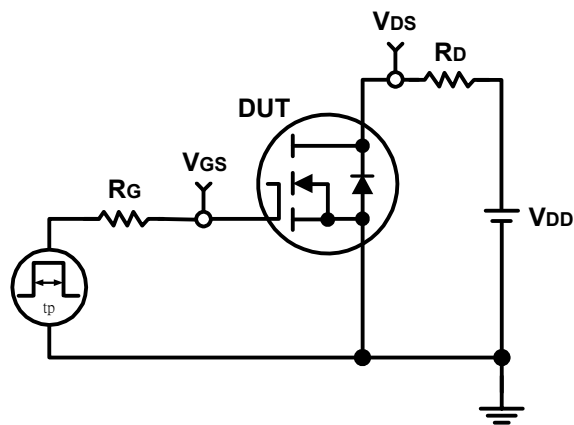
Source-Drain Diode Forward



Avalanche Test Circuit and Waveforms

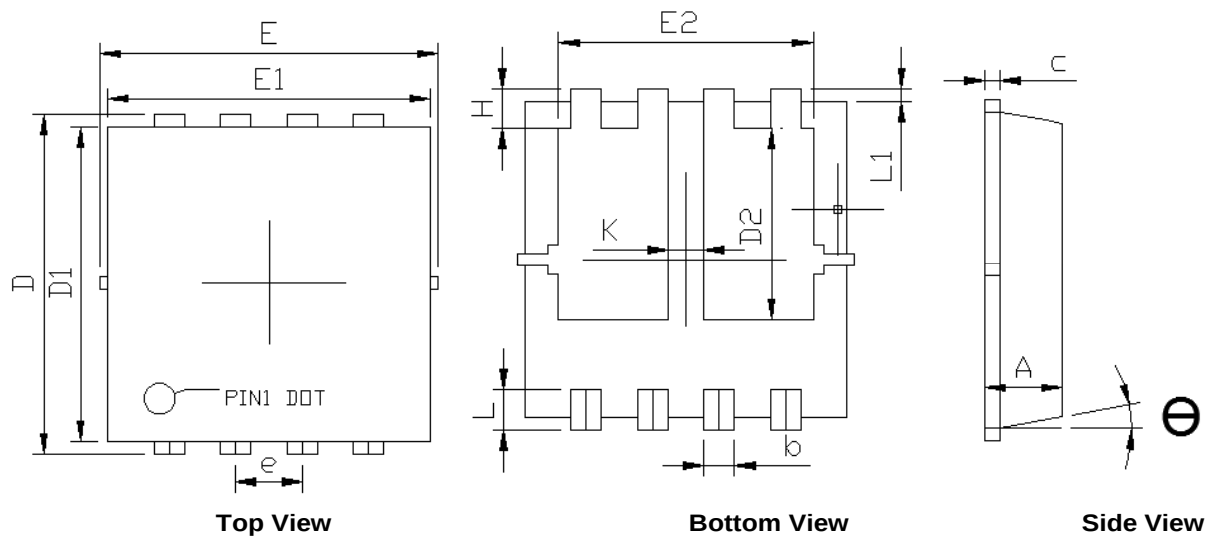


Switching Time Test Circuit and Waveforms



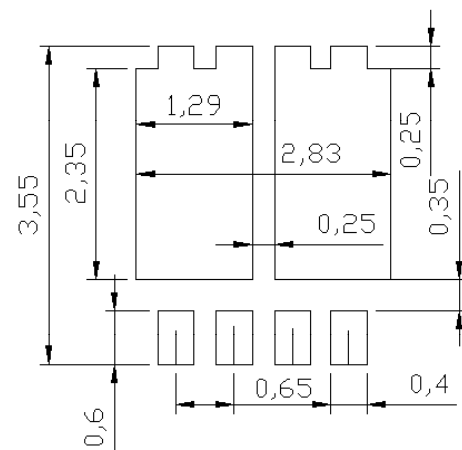
Package Information

DFN3.3x3.3-8L_EP2_P



SYMBOLS	DFN3.3x3.3G-8_EP2_P			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.70	0.80	0.028	0.031
b	0.25	0.35	0.010	0.014
c	0.10	0.25	0.004	0.010
D	3.25	3.45	0.128	0.136
D1	3.00	3.20	0.118	0.126
D2	1.78	1.98	0.070	0.078
E	3.20	3.40	0.126	0.134
E1	3.00	3.20	0.118	0.126
E2	2.39	2.59	0.094	0.102
e	0.65BSC		0.026 BSC	
H	0.30	0.50	0.012	0.020
L	0.30	0.50	0.012	0.020
L1	0.13 REF		0.005 REF	
K	0.30	-	0.012	-
θ	-	12°	-	12°

RECOMMENDED LAND PATTERN



UNIT: mm